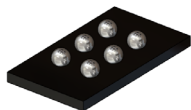


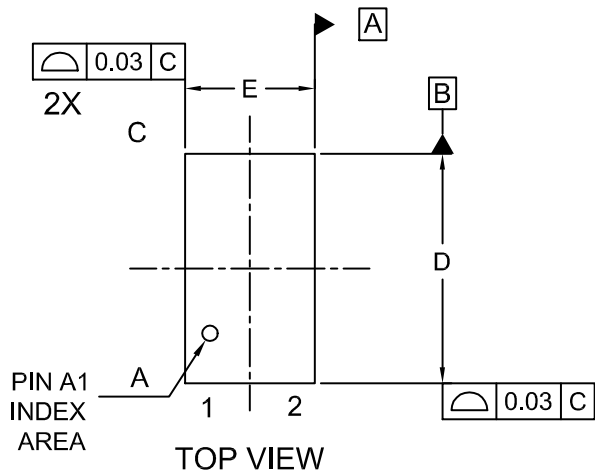
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



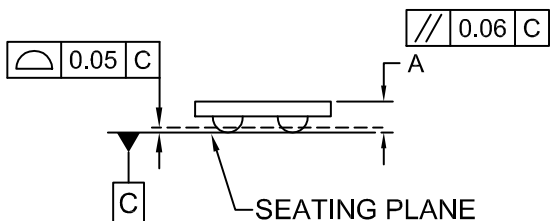
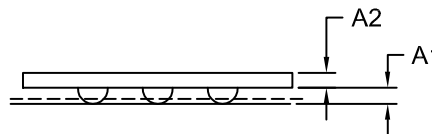
WLCSP6 2.3x1.3x0.35
CASE 567RE
ISSUE B

DATE 26 MAY 2022

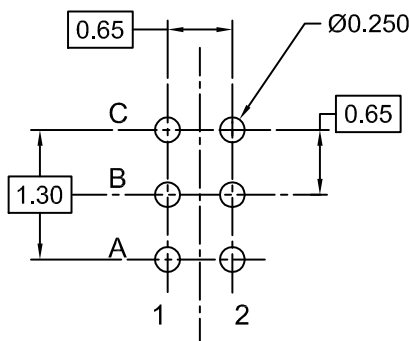
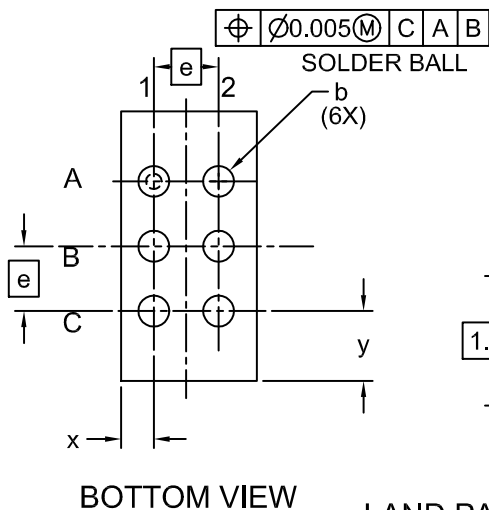


NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.35
A1	0.14	0.16	0.18
A2	0.13	0.15	0.17
b	0.27	0.30	0.33
D	2.23	2.28	2.33
E	1.23	1.28	1.33
e	0.65 BSC		
x	0.30	0.32	0.34
y	0.47	0.49	0.51



*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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